

## Technical Summary

Pacific Microchip Corp. has developed a power efficient 32-channel ASIC (1<sup>st</sup> generation) for X- and gamma-ray energy and timing measurement with a digital event building back-end.

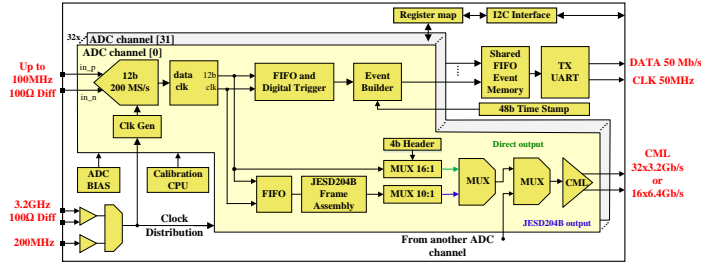


Figure 1. A block diagram of the ASIC.



Figure 2. A chip photo (left), expected BGA package view (center) and the package ball array (right).

The ASIC is targeted to support applications in single photon sensitive detector instruments for event related energy and timing measurement. To increase the commercialization potential, the ASIC can operate as an ADC array employing a JESD204B standard interface.

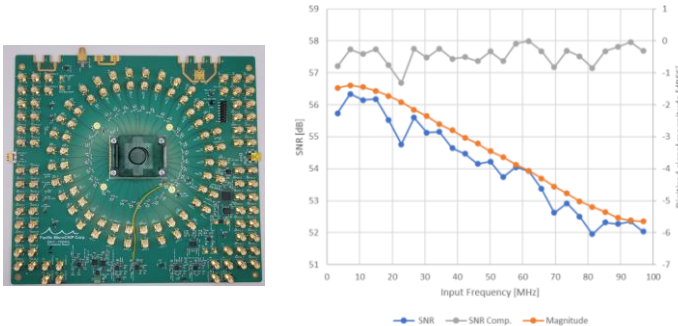


Figure 3. Evaluation PCB and measured ADC parameters.

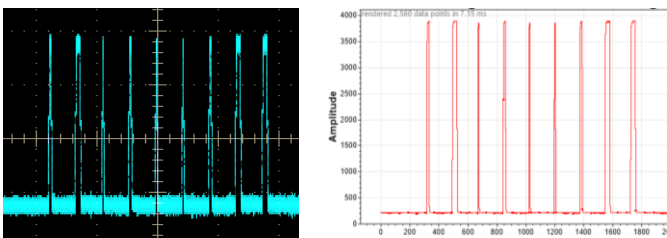


Figure 4. Pulses supplied to the ASIC channel (left). Pulses reconstructed from event builder data (right).

## Targeted Operational Capabilities

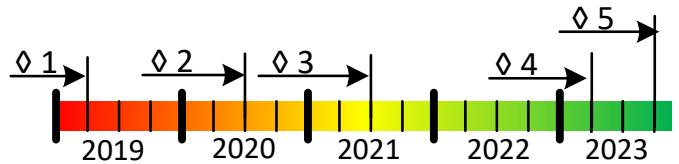
The ASIC offers low power consumption (4.5mW/ch) combined with complex functionality required for signal digitizing and extracting of event related data (time of arrival, threshold, time of peak, peak value, time over threshold, etc.). This data is assembled into packets and shipped out through an UART interface. Specific parameters/capabilities:

- 32 independently operated channels
- Programmable sampling rate of 200/100/50 MS/s
- 1Vpp differential input swing
- Digitizing ENOB up to 10-bit
- Input signal bandwidth > 0.2GHz
- Integrated 32ch event-building digital back-end
- RISK CPU for ADC calibration
- Optional direct ADC output through JESD204B interface
- Event data packet output through UART interface
- Power consumption < 4.5mW/channel (JESD204B is off)
- Total power with ADC data interface < 880mW.
- I2C interface for ASIC control
- Chip layout footprint 7.8mm<sup>2</sup>
- 15mm x 15mm 324 (18x18) ball BGA package

## Development Objectives & Milestones

The Phase I project demonstrated the feasibility of the ASIC. With the Phase II project the ASIC 1<sup>st</sup> prototype was designed, fabricated and tested. The achieved performance has not yet reached the target. The Phase IIB project will produce the ASIC 2<sup>nd</sup> prototype fixing current chip deficiencies. The project milestones include:

- ◇ 1. Feasibility is proven based on simulations (Ph. I)
- ◇ 2. Prototype chip is designed and taped out (Ph. II)
- ◇ 3. Prototype chip is fabricated and tested (Ph. II)
- ◇ 4. Final chip is designed and taped out (Ph. IIB)
- ◇ 5. Final chip is fabricated, tested, and sales start (Ph. IIB)



## Applications

- Detector streaming readout
- Multichannel gamma-ray spectroscopy systems
- X-ray detectors
- CT systems, luggage, and cargo scanners
- Synthetic aperture spectrometer instruments
- Test and measurement instrumentation
- Multichannel data acquisition devices
- Synthetic aperture radars and lidars